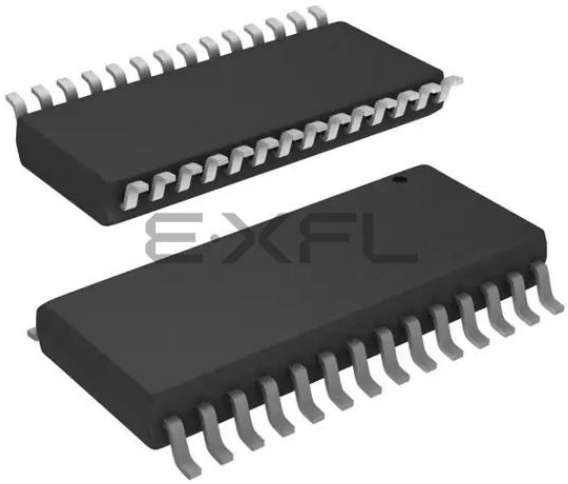

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	21
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj12mc202-e-so

The dsPIC33FJ12MC201/202 supports 16/16 and 32/16 divide operations, both fractional and integer. All divide instructions are iterative operations. They must be executed within a REPEAT loop, resulting in a total execution time of 19 instruction cycles. The divide operation can be interrupted during any of those 19 cycles without loss of data.

A 40-bit barrel shifter is used to perform up to a 16-bit left or right shift in a single cycle. The barrel shifter can be used by both MCU and DSP instructions.

FIGURE 3-1: dsPIC33FJ12MC201/202 CPU CORE BLOCK DIAGRAM

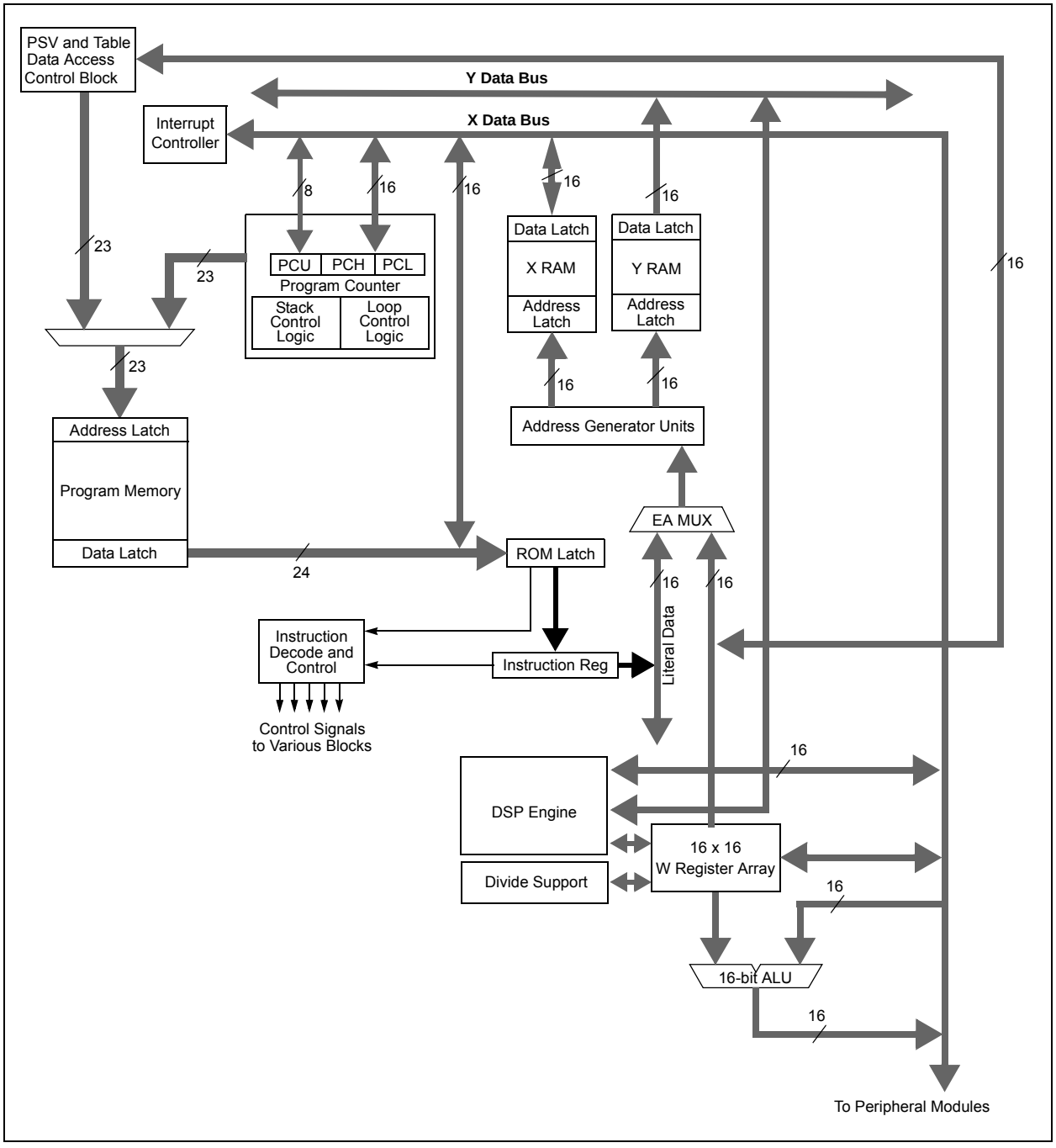


TABLE 4-19: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33FJ12MC201

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	06C0	—	—	—	RP1R<4:0>					—	—	—	RP0R<4:0>					0000
RPOR2	06C4	—	—	—	—	—	—	—	—	—	—	—	RP4R<4:0>					0000
RPOR3	06C6	—	—	—	RP7R<4:0>					—	—	—	—	—	—	—	—	0000
RPOR4	06C8	—	—	—	RP9R<4:0>					—	—	—	RP8R<4:0>					0000
RPOR6	06CC	—	—	—	RP13R<4:0>					—	—	—	RP12R<4:0>					0000
RPOR7	06CE	—	—	—	RP15R<4:0>					—	—	—	RP14R<4:0>					0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: PORTA REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	02C0	—	—	—	—	—	—	—	—	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	001F
PORTA	02C2	—	—	—	—	—	—	—	—	—	—	—	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	02C4	—	—	—	—	—	—	—	—	—	—	—	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	02C6	—	—	—	—	—	—	—	—	—	—	—	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-21: PORTB REGISTER MAP FOR dsPIC33FJ12MC202

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	02CA	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	02CC	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	02CE	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: PORTB REGISTER MAP FOR dsPIC33FJ12MC201

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	02C8	TRISB15	TRISB14	TRISB13	TRISB12	—	—	TRISB9	TRISB8	TRISB7	—	—	TRISB4	—	—	TRISB1	TRISB0	F393
PORTB	02CA	RB15	RB14	RB13	RB12	—	—	RB9	RB8	RB7	—	—	RB4	—	—	RB1	RB0	xxxx
LATB	02CC	LATB15	LATB14	LATB13	LATB12	—	—	LATB9	LATB8	LATB7	—	—	LATB4	—	—	LATB1	LATB0	xxxx
ODCB	02CE	ODCB15	ODCB14	ODCB13	ODCB12	—	—	ODCB9	ODCB8	ODCB7	—	—	ODCB4	—	—	ODCB1	ODCB0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal

REGISTER 5-2: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:	SO = Settable only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register (write-only) bits

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Use alternate vector table
0 = Use standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 7-9: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ12MC201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ12MC201/202 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. dsPIC33FJ12MC201/202 devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

dsPIC33FJ12MC201/202 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

dsPIC33FJ12MC201/202 devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to wake-up.

9.2.1 SLEEP MODE

The following occur in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled
- The LPRC clock continues to run in Sleep mode if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled

The device will wake-up from Sleep mode on any of the these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

10.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33FJ12MC201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "I/O Ports"** (DS70193) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

All of the device pins (except VDD, VSS, $\overline{\text{MCLR}}$, and OSC1/CLKI) are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

10.1 Parallel I/O (PIO) Ports

Generally a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through," in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 10-1 shows how ports are shared with other peripherals and the associated I/O pin to which they are connected.

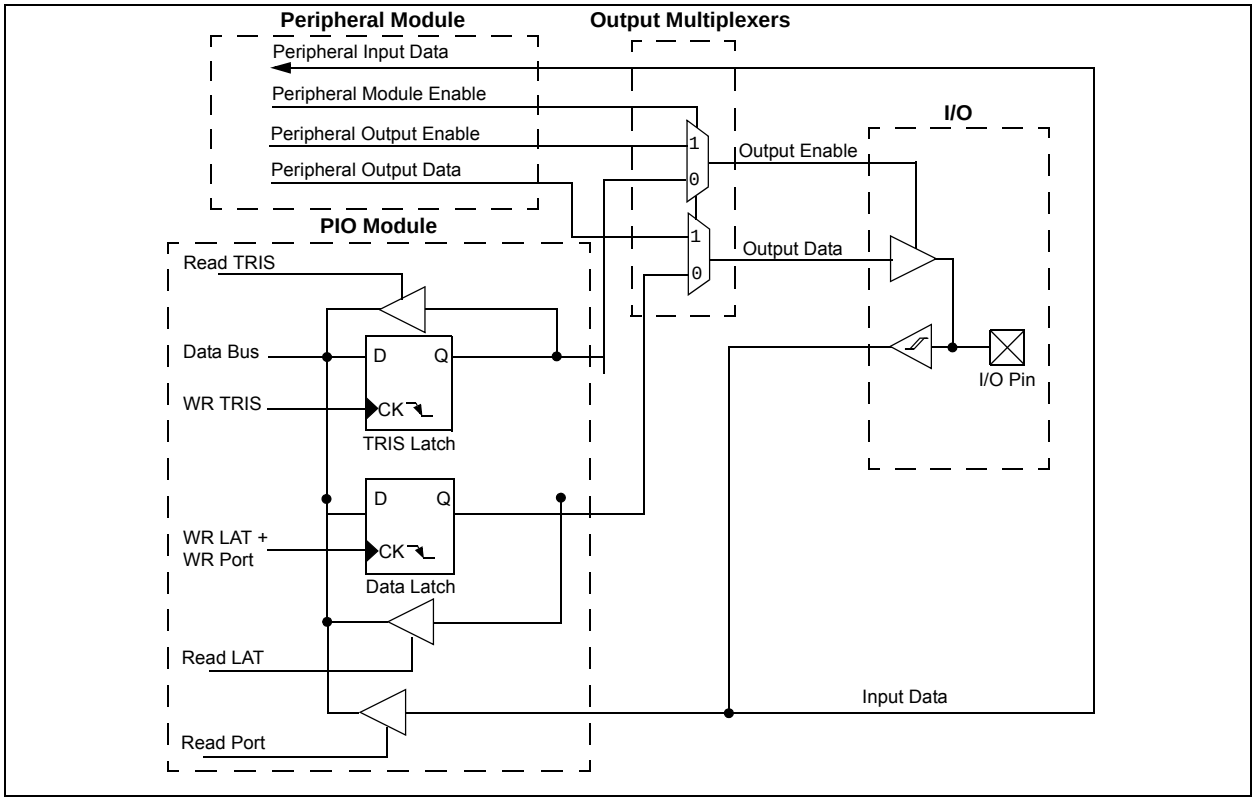
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. This means the corresponding LATx and TRISx registers and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

FIGURE 10-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



REGISTER 10-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T3CKR<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T2CKR<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **T3CKR<4:0>:** Assign Timer3 External Clock (T3CK) to the corresponding RPn pin
11111 = Input tied Vss
01111 = Input tied to RP15
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **T2CKR<4:0>:** Assign Timer2 External Clock (T2CK) to the corresponding RPn pin
11111 = Input tied Vss
01111 = Input tied to RP15
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0 HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM<2:0>		
bit 7							bit 0

Legend:	HC = Cleared in Hardware	HS = Set in Hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x will halt in CPU Idle mode
0 = Output Compare x will continue to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred
(This bit is only used when OCM<2:0> = 111.)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Compare x
0 = Timer2 is the clock source for Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin enabled
110 = PWM mode on OCx, Fault pin disabled
101 = Initialize OCx pin low, generate continuous output pulses on OCx pin
100 = Initialize OCx pin low, generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high, compare event forces OCx pin low
001 = Initialize OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

21.2 On-Chip Voltage Regulator

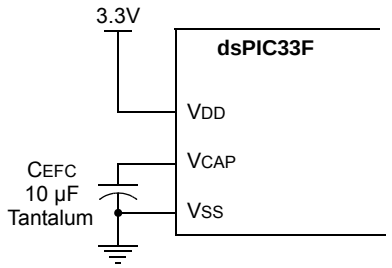
All of the dsPIC33FJ12MC201/202 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ12MC201/202 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 21-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 24-13 located in **Section 24.1 "DC Characteristics"**.

Note:	It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 21-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to **Section TABLE 24-13: "Internal Voltage Regulator Specifications"** located in **Section 24.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

21.3 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines, or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

FIGURE 24-2: EXTERNAL CLOCK TIMING

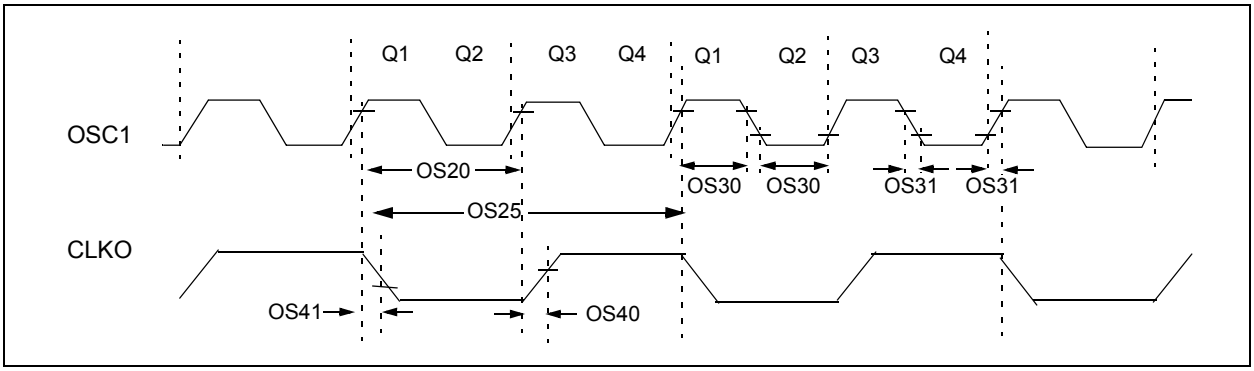


TABLE 24-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	40	MHz	EC
		Oscillator Crystal Frequency	3.5 10 —	— — —	10 40 33	MHz MHz kHz	XT HS SOSC
OS20	TOSC	TOSC = 1/FOSC	12.5	—	DC	ns	
OS25	TCY	Instruction Cycle Time(2,4)	25	—	DC	ns	
OS30	TosL, TosH	External Clock in (OSC1)(5) High or Low Time	0.375 x TOSC	—	0.625 x TOSC	ns	EC
OS31	TosR, TosF	External Clock in (OSC1)(5) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3,5)	—	5.2	—	ns	—
OS41	TckF	CLKO Fall Time(3,5)	—	5.2	—	ns	—
OS42	GM	External Oscillator Transconductance(4)	14	16	18	mA/V	VDD = 3.3V TA = +25ºC

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: Instruction cycle period (TCY) equals two times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: These parameters are characterized by similarity, but are tested in manufacturing at FIN = 40 MHz only.

5: These parameters are characterized by similarity, but are not tested in manufacturing.

6: Data for this parameter is Preliminary. This parameter is characterized, but not tested in manufacturing.

TABLE 24-28: SIMPLE OC/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	TCY + 20	ns	—
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	—

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing.

FIGURE 24-10: MOTOR CONTROL PWM MODULE FAULT TIMING CHARACTERISTICS

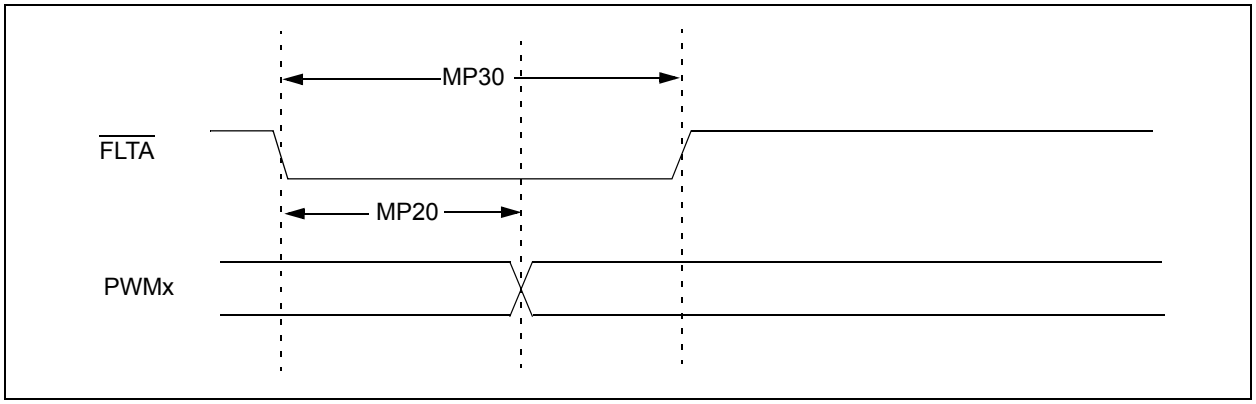
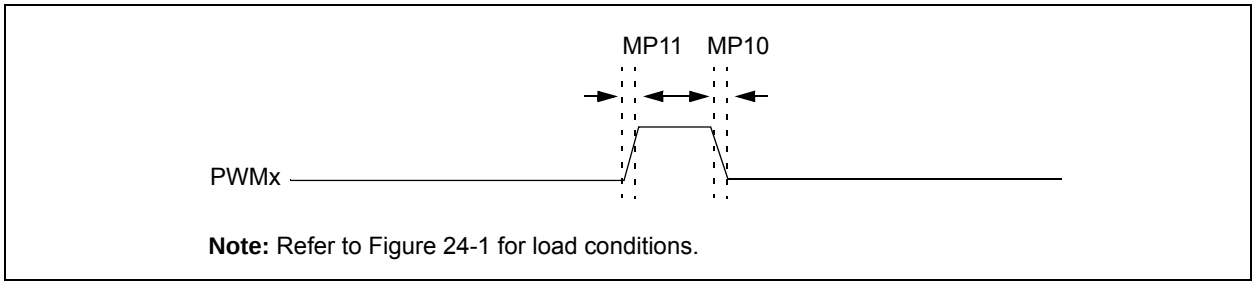
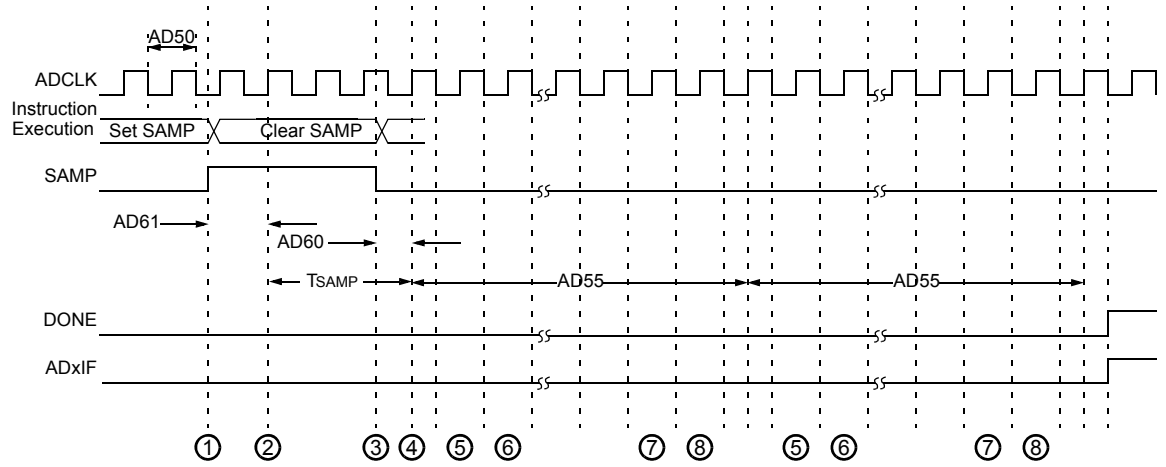


FIGURE 24-11: MOTOR CONTROL PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

FIGURE 24-27: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



1 – Software sets ADxCON. SAMP to start sampling.

2 – Sampling starts after discharge period. TSAMP is described in S**ection 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual*".

3 – Software clears ADxCON. SAMP to start conversion.

4 – Sampling ends, conversion sequence starts.

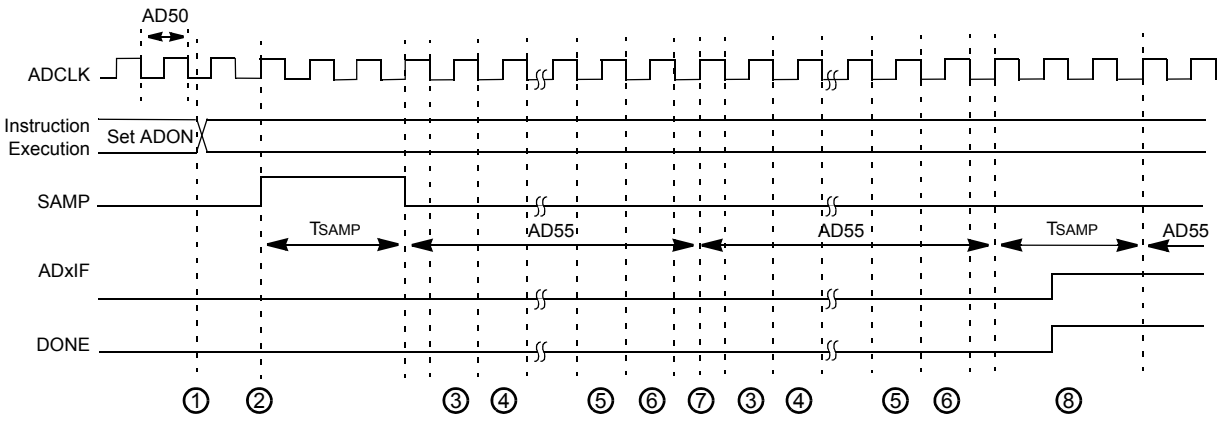
5 – Convert bit 9.

6 – Convert bit 8.

7 – Convert bit 0.

8 – One TAD for end of conversion.

FIGURE 24-28: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



1 – Software sets ADxCON. ADON to start AD operation.

2 – Sampling starts after discharge period. TSAMP is described in S**ection 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *'dsPIC33F/PIC24H Family Reference Manual"*.

3 – Convert bit 9.

4 – Convert bit 8.

5 – Convert bit 0.

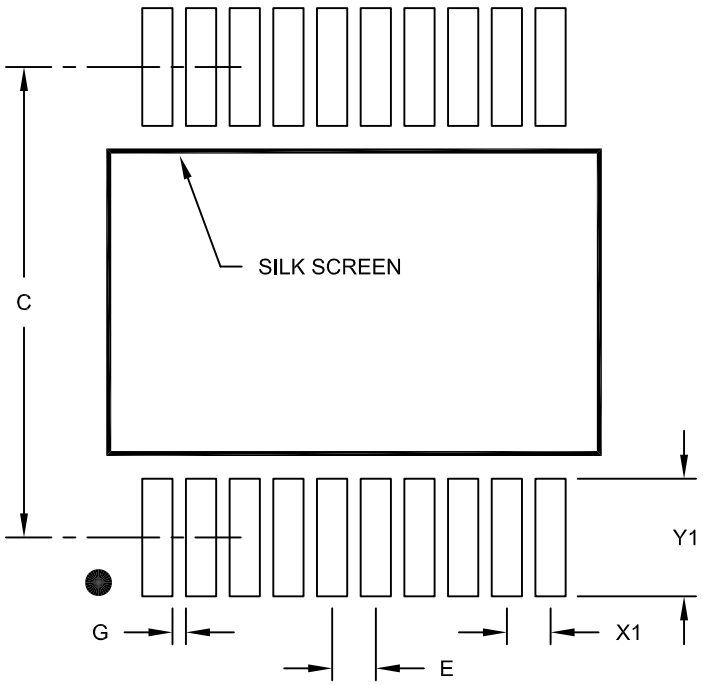
6 – One TAD for end of conversion.

7 – Begin conversion of next channel.

8 – Sample for time specified by SAMC<4:0>.

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

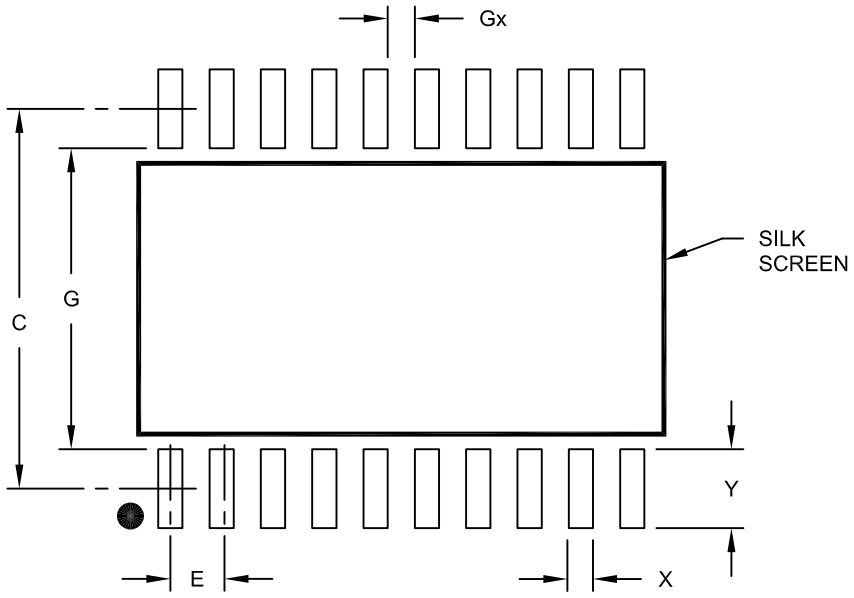
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072A

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.45		

Notes:

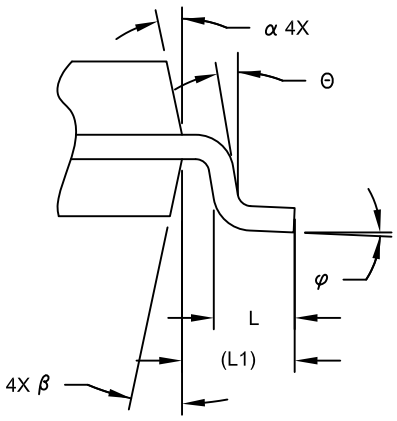
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

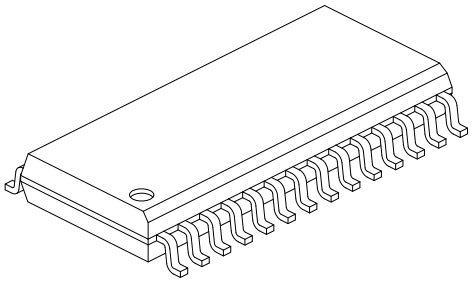
Microchip Technology Drawing No. C04-2094A

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

TABLE 25-1: MAJOR SECTION UPDATES

Section Name	Update Description
Section 9.0 "I/O Ports"	Added paragraph and Table 9-1 to **Section 9.1.1 "Open-Drain Configuration"**, which provides details on I/O pins and their functionality. Removed the following sections, which are now available in the related section of the dsPIC33F Family Reference Manual: • 9.4.2 "Available Peripherals" • 9.4.3.3 "Mapping" • 9.4.5 "Considerations for Peripheral Pin Selection"
Section 13.0 "Output Compare"	Replaced sections 13.1, 13.2, and 13.3 and related figures and tables with entirely new content.
Section 14.0 "Motor Control PWM Module"	Removed the following sections, which are now available in the related section of the dsPIC33F Family Reference Manual: • 14.3 "PWM Time Base • 14.4 "PWM Period" • 14.5 "Edge-Aligned PWM" • 14.6 "Center-Aligned PWM" • 14.7 "PWM Duty Cycle Comparison Units" • 14.8 "Complementary PWM Operation" • 14.9 "Dead-Time Generators" • 14.10 "Independent PWM Output" • 14.11 "Single Pulse PWM Operation" • 14.12 "PWM Output Override" • 14.13 "PWM Output and Polarity Control • 14.14 "PWM Fault Pins" • 14.15 "PWM Update Lockout" • 14.16 "PWM Special Event Trigger" • 14.17 "PWM Operation During CPU Sleep Mode" • 14.18 "PWM Operation During CPU Idle Mode
Section 15.0 "Quadrature Encoder Interface (QEI) Module"	Removed the following sections, which are now available in the related section of the dsPIC33F Family Reference Manual: • 15.1 "Quadrature Encoder Interface Logic" • 15.2 "16-bit Up/Down Position Counter Mode" • 15.3 "Position Measurement Mode" • 15.4 "Programmable Digital Noise Filters" • 15.5 "Alternate 16-bit Timer/Counter" • 15.6 QEI Module Operation During CPU Sleep Mode" • 15.7 "QEI Module Operation During CPU Idle Mode" • 15.8 "Quadrature Encoder Interface Interrupts"
Section 16.0 "Serial Peripheral Interface (SPI)"	Removed the following sections, which are now available in the related section of the dsPIC33F Family Reference Manual: • 16.1 "Interrupts" • 16.2 "Receive Operations" • 16.3 "Transmit Operations" • 16.4 "SPI Setup: Master Mode" • 16.5 "SPI Setup: Slave Mode" (retained Figure 16-1: SPI Module Block Diagram)

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